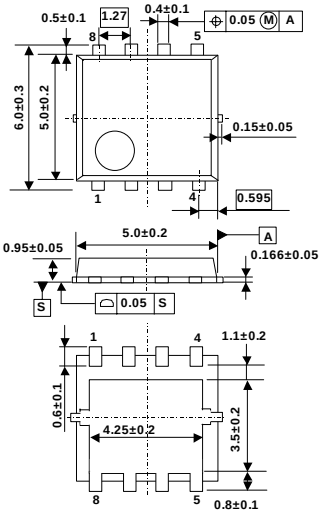
TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (Ultra-High-Speed U-MOSIII)

TPCA8016-H

High-Speed and High-Efficiency DC-DC Converters
Notebook PC Applications
Portable Equipment Applications

- Small footprint due to small and thin package
- High-speed switching
- Small gate charge: Qsw = 6.6 nC (typ.)
- Low drain-source ON resistance: $R_{DS\ (ON)}$ = 16 mΩ (typ.)
- High forward transfer admittance: $|Y_{fs}|$ = 40 S (typ.)
- Low leakage current: I_{DSS} = 10 μA (max) (V_{DS} = 60 V)
- Enhancement mode: V_{th} = 1.1 to 2.3 V (V_{DS} = 10 V, I_D = 1 mA)

Unit: mm



1,2,3 : SOURCE 4 : GATE
5,6,7,8 : DRAIN

JEDEC	—
JEITA	—
TOSHIBA	2-5Q1A

Weight: 0.080 g (typ.)

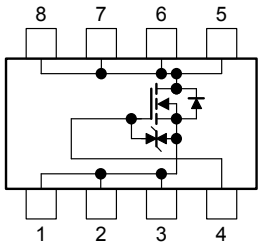
Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	V
Drain-gate voltage (R_{GS} = 20 kΩ)		V_{DGR}	60	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC (Note 1)	I_D	25	A
	Pulsed (Note 1)	I_{DP}	75	
Drain power dissipation (Tc = 25°C)		P_D	45	W
Drain power dissipation (t = 10 s) (Note 2a)		P_D	2.8	W
Drain power dissipation (t = 10 s) (Note 2b)		P_D	1.6	W
Single pulse avalanche energy (Note 3)		E_{AS}	45	mJ
Avalanche current		I_{AR}	25	A
Repetitive avalanche energy (Tc=25°C) (Note 4)		E_{AR}	2.7	mJ
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	−55 to 150	°C

Note: For Notes 1to 5, refer to the next page.

This transistor is an electrostatic-sensitive device. Handle with caution.

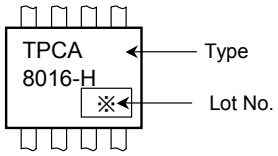
Circuit Configuration



Thermal Characteristics

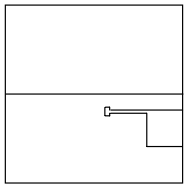
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25°C)	$R_{th\ (ch\text{-}c)}$	2.78	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	$R_{th\ (ch\text{-}a)}$	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	$R_{th\ (ch\text{-}a)}$	78.1	°C/W

Marking (Note 5)



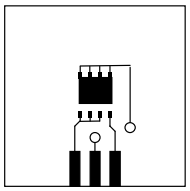
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

(a)



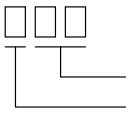
FR-4
25.4 × 25.4 × 0.8
(Unit: mm)

(b)

Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 0.1 mH, R_G = 25 Ω, I_{AR} = 25 A

Note 4: Repetitive rating: pulse width limited by max channel temperature

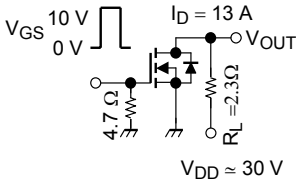
Note 5: * Weekly code: (Three digits)



Week of manufacture
(01 for the first week of the year, continuing up to 52 or 53)

Year of manufacture
(The last digit of the year)

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{GS} = ±16 V, V_{DS} = 0 V	—	—	±10	μA
Drain cut-OFF current		I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V	—	—	10	μA
Drain-source breakdown voltage		$V_{(BR)\ DSS}$	I_D = 10 mA, V_{GS} = 0 V	60	—	—	V
		$V_{(BR)\ DSX}$	I_D = 10 mA, V_{GS} = −20 V	45	—	—	
Gate threshold voltage		V_{th}	V_{DS} = 10 V, I_D = 1 mA	1.1	—	2.3	V
Drain-source ON resistance		$R_{DS\ (ON)}$	V_{GS} = 10 V, I_D = 13 A	—	16	21	mΩ
			V_{GS} = 4.5 V, I_D = 13 A	—	20	26	
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = 10 V, I_D = 13 A	20	40	—	S
Input capacitance		C_{iss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	—	1375	—	pF
Reverse transfer capacitance		C_{rss}		—	70	—	
Output capacitance		C_{oss}		—	340	—	
Gate resistance		R_g		—	1.0	—	Ω
Switching time	Rise time	t_r	 Duty ≦ 1%, t_w = 10 μs	—	4	—	ns
	Turn-ON time	t_{on}		—	10	—	
	Fall time	t_f		—	3	—	
	Turn-OFF time	t_{off}		—	19	—	
Total gate charge (gate-source plus gate-drain)		Q_g	V_{DD} ≃ 48 V, V_{GS} = 10 V, I_D = 25 A	—	22	—	nC
			V_{DD} ≃ 48 V, V_{GS} = 5 V, I_D = 25 A	—	12	—	
Gate-source charge 1		Q_{gs1}	V_{DD} ≃ 48 V, V_{GS} = 10 V, I_D = 25 A	—	4.6	—	
Gate-drain (“miller”) charge		Q_{gd}		—	4.2	—	
Gate switch charge		Q_{SW}		—	6.6	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	Pulse (Note 1)	I_{DRP}	—	—	—	75	A
Forward voltage (diode)		V_{DSF}	I_{DR} = 25 A, V_{GS} = 0 V	—	—	−1.2	V

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